SS IEC 60749-1:2025
IEC 60749-1:2002, IDT
(ICS 31.080.01)

SINGAPORE STANDARD

Semiconductor devices – Mechanical and climatic test methods

– Part 1: General

Singapore Standards Council

SS IEC 60749-1:2025
IEC 60749-1:2002, IDT
(ICS 31.080.01)

SINGAPORE STANDARD

Semiconductor devices – Mechanical and climatic test methods

– Part 1: General

Published by Enterprise Singapore

ISBN 978-981-5277-81-4

National Foreword

This Singapore Standard was prepared by the Working Group on Semiconductor Devices set up by the Technical Committee on Electrical and Electronic Products under the purview of the Electrical and Electronic Standards Committee.

This standard is an identical adoption of IEC 60749-1:2002, “Semiconductor devices – Mechanical and climatic test methods – Part 1: General”, published by the International Electrotechnical Commission.

Attention is drawn to the possibility that some of the elements of this Singapore Standard may be the subject of patent rights. Enterprise Singapore shall not be held responsible for identifying any or all of such patent rights.

NOTE

1. *Singapore Standards (SSs) and Technical References (TRs) are reviewed periodically to keep abreast of technical changes, technological developments and industry practices. The changes are documented through the issue of either amendments or revisions. Where SSs are deemed to be stable, i.e. no foreseeable changes in them, they will be classified as “mature standards”. Mature standards will not be subject to further review, unless there are requests to review such standards.*

2. *An SS or TR is voluntary in nature except when it is made mandatory by a regulatory authority. It can also be cited in contracts making its application a business necessity. Users are advised to assess and determine whether the SS or TR is suitable for their intended use or purpose. If required, they should refer to the relevant professionals or experts for advice on the use of the document. Enterprise Singapore and the Singapore Standards Council shall not be liable for any damages whether directly or indirectly suffered by anyone or any organisation as a result of the use of any SS or TR. Although care has been taken to draft this standard, users are also advised to ensure that they apply the information after due diligence.*

3. *Compliance with a SS or TR does not exempt users from any legal obligations.*

INTERNATIONAL STANDARD

CEI IEC 60749-1

First edition
2002-08

Semiconductor devices – Mechanical and climatic test methods –

Part 1: General

Reference number
CEI/IEC 60749-1:2002

Publication numbering

As from 1 January 1997 all IEC publications are issued with a designation in the 60000 series. For example, IEC 34-1 is now referred to as IEC 60034-1.

Consolidated editions

The IEC is now publishing consolidated versions of its publications. For example, edition numbers 1.0, 1.1 and 1.2 refer, respectively, to the base publication, the base publication incorporating amendment 1 and the base publication incorporating amendments 1 and 2.

Further information on IEC publications

The technical content of IEC publications is kept under constant review by the IEC, thus ensuring that the content reflects current technology. Information relating to this publication, including its validity, is available in the IEC Catalogue of publications (see below) in addition to new editions, amendments and corrigenda. Information on the subjects under consideration and work in progress undertaken by the technical committee which has prepared this publication, as well as the list of publications issued, is also available from the following:

- **IEC Web Site (www.iec.ch)**
- **Catalogue of IEC publications**

  The on-line catalogue on the IEC web site (http://www.iec.ch/searchpub/cur_fut.htm) enables you to search by a variety of criteria including text searches, technical committees and date of publication. On-line information is also available on recently issued publications, withdrawn and replaced publications, as well as corrigenda.

- **IEC Just Published**

  This summary of recently issued publications (http://www.iec.ch/online_news/justpub/jp_entry.htm) is also available by email. Please contact the Customer Service Centre (see below) for further information.

- **Customer Service Centre**

  If you have any questions regarding this publication or need further assistance, please contact the Customer Service Centre:

  Email: custserv@iec.ch
  Tel: +41 22 919 02 11
  Fax: +41 22 919 03 00

INTERNATIONAL STANDARD

CEI IEC 60749-1

First edition
2002-08

Semiconductor devices – Mechanical and climatic test methods –

Part 1: General

International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch

Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

CODE PRIX
PRICE CODE H

For price, see current catalogue

CONTENTS

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 1: General

FOREWORD

1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
2) The formal decisions or agreements of the IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested National Committees.
3) The documents produced have the form of recommendations for international use and are published in the form of standards, technical specifications, technical reports or guides and they are accepted by the National Committees in that sense.
4) In order to promote international unification, IEC National Committees undertake to apply IEC International Standards transparently to the maximum extent possible in their national and regional standards. Any divergence between the IEC Standard and the corresponding national or regional standard shall be clearly indicated in the latter.
5) The IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with one of its standards.
6) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. The IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 60749-1 has been prepared by IEC technical committee 47: Semiconductor devices.

This first edition of IEC 60749-1, as well as the other parts of this series, will replace the previous edition of IEC 60749 in which the test methods were contained in one standard which was subdivided into chapters relating to mechanical test methods, climatic test methods and miscellaneous test methods.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1638/FDIS	47/1653/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

Each test method governed by this standard and which is part of the series is a stand-alone document, numbered IEC 60749-2, IEC 60749-3, etc. The numbering of these test methods is sequential, and there is no relationship between the number and the test method (i.e. no grouping of test methods). The list of these tests will be available in the IEC Internet site and in the catalogue.

Updating of any of the individual test methods is independent of any other part.

The committee has decided that the contents of this publication will remain unchanged until 2007. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

The contents of the corrigendum of August 2003 have been included in this copy.

INTRODUCTION

Activity within IEC technical committee 47, working group 2, includes the generation, coordination and review of climatic, electrical (of which only ESD, latch-up and electrical conditions for life tests are considered), mechanical test methods, and associated inspection techniques needed to assess the quality and reliability of the design and manufacture of semiconductor products and processes.

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 1: General

1 Scope

This part of IEC 60749 is applicable to semiconductor devices (discrete devices and integrated circuits) and establishes provisions common to all the other parts of the series.

In the case of contradiction between this standard and a relevant procurement specification, the latter should govern.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050 (all parts), *International Electrotechnical Vocabulary (IEV)*

IEC 60747 (all parts), *Semiconductor devices – Discrete devices*

IEC 60748 (all parts), *Semiconductor devices – Integrated circuits*